- 100K Compatible
- ECL and TTL Control Inputs
- Noninverting Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Center Pin V_{CC}, V_{EE}, and GND Configurations Minimize High-Speed Switching Noise
- Package Options Include "Small Outline" Packages and Standard Plastic 300-mil DIPs

description

This octal ECL-to-TTL translator is designed to provide a efficient translation between a 100K ECL signal environment to a TTL signal environment. This device is designed specifically to improve the performance and density of ECL-to-TTL CPU/bus-oriented functions such as memory-address drivers, clock drivers, and bus-oriented receivers and transmitters.

Two output-enable pins, $\overline{OE}1$ and $\overline{OE}2$ are provided. These control inputs are ANDed together with $\overline{OE}1$ being ECL compatible and $\overline{OE}2$ being TTL compatible. This offers the choice of controlling the outputs of the device from either a TTL or ECL signal environment.

The SN100KT5541 is characterized for operation from 0°C to 85°C.

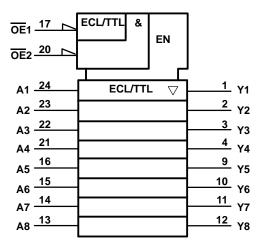
FUNCTION TABLE

OUT	PUT	DATA	OUTPUT
ENA	BLE	INPUT	(TTL)
OE1	OE2	Α	Y
Х	Н	Х	Z
Н	Х	Х	Z
L	L	L	L
L	L	Н	Н

(TOP VIEW) 24 A1 Y2 **∏** 2 23 🛮 A2 Y3 **∏** 3 22 A3 Y4 ∏ 21 A4 20 OE2 (TTL) GND 6 19 V_{EE} GND 7 18 GND 17 OE1 (ECL) GND **∏** 8 Y5 **∏** 9 16 A5 Y6 7 10 15 A6 Y7 🛭 14 A7 11 Y8 **∏** 12 13 A8

DW OR NT PACKAGE

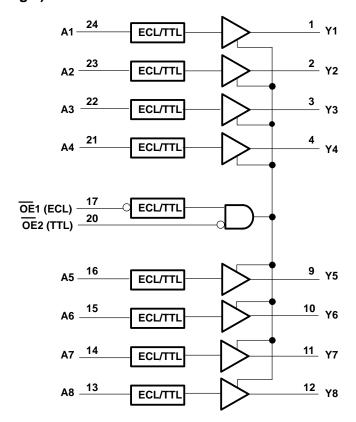
logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	$-0.5\ V$ to 7 V
Supply voltage range, V _{EE}	
Input voltage range (TTL) (see Note 1)	$-1.2\ V$ to 7 V
Input voltage range (ECL)	V_{EE} to 0 V
Voltage applied to any output in the high state	\dots -0.5 V to V _{CC}
Voltage applied to any output in the disabled or power-off state	\ldots $-0.5\ V$ to 5.5 V
Input current range (TTL)	\dots -30 mA to 5 mA
Current into any output in the low state	96 mA
Operating free-air temperature range	0°C to 85°C
Storage temperature range	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The TTL input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	TTL supply voltage	4.5	5	5.5	V
VEE	ECL supply voltage	-4.2	-4.5	-4.8	V
VIH	TTL high-level input voltage	2			V
V _{IL}	TTL low-level input voltage			0.8	V
VIH	ECL high-level input voltage [‡]	-1150		-840	mV
V _{IL}	ECL low-level input voltage [‡]	-1810		-1490	mV
lıK	TTL input clamp current			-18	mA
IOH	High-level output current			-15	mA
loL	Low-level output current			48	mA
TA	Operating free-air temperature	0		85	°C

[‡] The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic levels only.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	6	MIN	TYP [†]	MAX	UNIT
VIK	OE2 only	$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -4.2 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2	V
II	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	V _I = 7 V			0.1	mA
lн	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	V _I = 2.7 V			20	μΑ
I _{IL}	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	V _I = 0.5 V			-0.5	mA
lіН	Data inputs and OE1	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	$V_{IH} = -840 \text{ mV}$			350	μΑ
I _{IL}	Data inputs and OE1	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	$V_{IL} = -1810 \text{ mV}$	0.50			μΑ
\/ - · ·		$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -4.5 \text{ V} \pm 0.3 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.4	3.3		V
VOH		$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -4.5 \text{ V} \pm 0.3 \text{ V},$	$I_{OH} = -15 \text{ mA}$	2	3.1		V
VOL		$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -4.5 \text{ V} \pm 0.3 \text{ V},$	$I_{OL} = 48 \text{ mA}$		0.38	0.55	V
lozh		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	$V_0 = 2.7 \text{ V}$			50	μΑ
lozL		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	$V_0 = 0.5 V$			-50	μΑ
los‡		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V},$	VO = 0 V	-100		-225	mA
ICCH		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V}$			64	97	mA
ICCL		$V_{CC} = 5.5 \text{ V},$	V _{EE} = -4.8 V			80	120	mA
ICCZ		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V}$			77	116	mA
IEE		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -4.8 \text{ V}$			-22	-33	mA
Ci		$V_{CC} = 5 V$,	V _{EE} = 4.5 V			5		pF
Co		$V_{CC} = 5 V$,	V _{EE} = 4.5 V			7		pF

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	R1 = 500 Ω , R2 = 500 Ω		C _L = 50 pF, R1 = 500 Ω , R2 = 500 Ω		UNIT
			MIN	TYP§	MAX		
^t PLH	Α	Y	1.7	4	6.2	ns	
^t PHL		'	1.6	4	6.2	113	
^t PZH	OE1	Υ	2.6	4.7	6.7	20	
^t PZL		, , ,	3.2	5.9	8.5	ns	
^t PHZ	ŌE1	V	2.9	5.4	7.8	ns	
^t PLZ		'	1.9	4.9	7.8	113	
^t PZH	OE2	Υ	1.7	4	6.2	ns	
^t PZL		1	2.5	5.1	7.7	115	
t _{PHZ}	OE2	Υ	2.1	4.3	6.4		
t _{PLZ}		Y	1.1	3.7	6.3	ns	

[§] All typical values are at $V_{CC} = 5 \text{ V}$, $V_{EE} = -4.5 \text{ V}$, $T_A = 25^{\circ}C$.

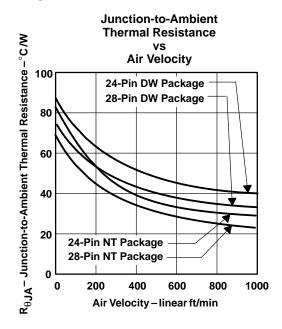


[†] All typical values are at V_{CC} = 5 V, V_{EE} = -4.5 V, T_A = 25°C. ‡ Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

THERMAL INFORMATION

In digital system designs utilizing 100KT' or 10KHT' logic level translators, good thermal management is an important consideration for proper circuit performance and extended reliability. The size of outline" package makes thermal the "small management even more important due to the increased board and thermal densities.

The thermal resistances in Figure 1 can be used to approximate typical and maximum virtual junction temperatures for the SN100KT' and SN10KHT' translators. The junction temperature of these devices may be estimated using Equation 1.



$$T_{J} = R_{\Theta JA} (V_{CC} \bullet I_{CC} + V_{EE} \bullet I_{EE} + P_{DRIVER}) + T_{A}$$
(1)

where

 T_J = virtual junction temperature

 T_A = ambient air temperature

 $R_{\Theta,JA}$ = thermal resistance, junction to ambient air

I_{CC} = TTL level supply current (from the databook)

IFF = ECL supply current

V_{CC} = TTL level suply voltage (5 V for typical, 5.5 V for maximum)

 V_{FF} = ECL level supply voltage:

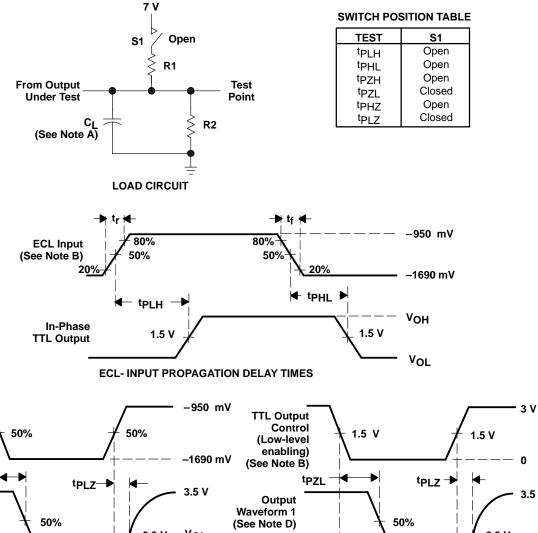
SN10KHT' - (-5.2 V Typ, -5.46 V Max)

SN100KHT' - (-54.5 V Typ, -4.80 V Max)

PDRIVER = total power consumed by the output driver



PARAMETER MEASUREMENT INFORMATION



tPZL 3.5 V Output Waveform 1 (See Note D) VOL VOL tPZH ' tPHZ → tPHZ ▶ ^tPZH VOH Output ۷он 0.3 V Waveform 2 Output 0.3 V 50% Waveform 2 (See Note D) 50% (See Note D) 0 0 TTL ENABLE AND DISABLE TIMES **ECL ENABLE AND DISABLE TIMES**

NOTES: A. CL includes probe and jig capacitance.

ECL Output

(Low-level

enabling)

Control

- B. For TTL inputs, input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, $t_{\Gamma} \leq$ 2.5 ns. $t_{\Gamma} \leq$ 2.5 ns.
- C. For ECL inputs, input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, $t_f \leq$ 1.5 ns, $t_f \leq$ 1.5 ns.
- D. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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